

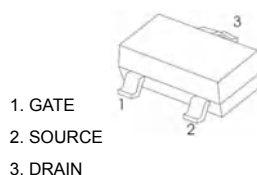
FEATURES

- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability

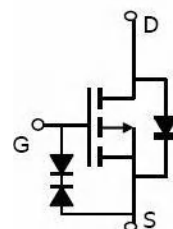
V_{DS} -20 V
 I_D -4.0 A
 $R_{DS(ON)}$ 30 m Ω

3415

SOT-23



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current ($t \leq 10\text{s}$)	I_D	-4.0	A
Maximum Power Dissipation ($t \leq 10\text{s}$)	P_D	1.2	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^\circ\text{C}$

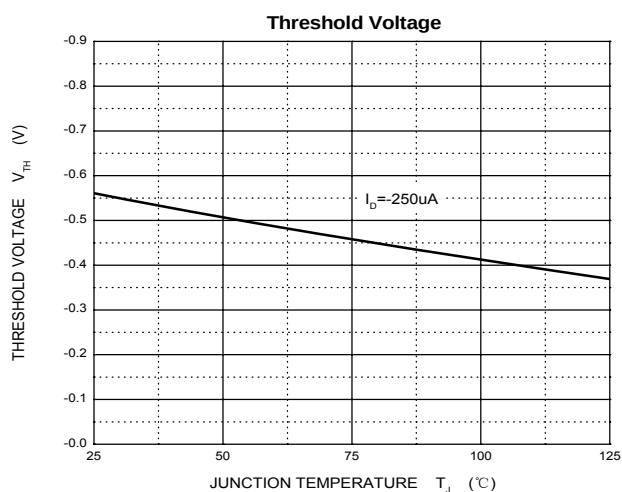
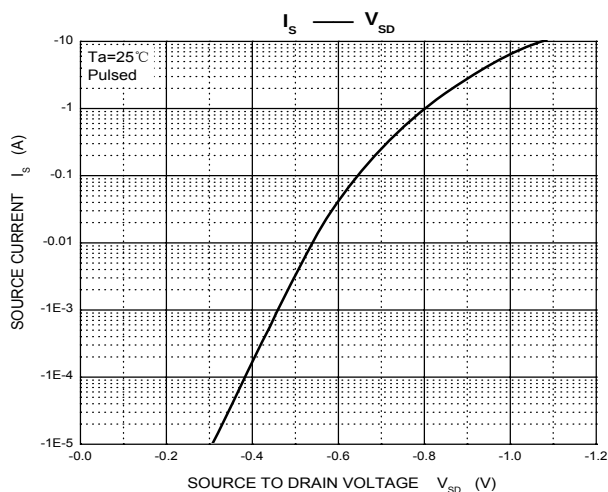
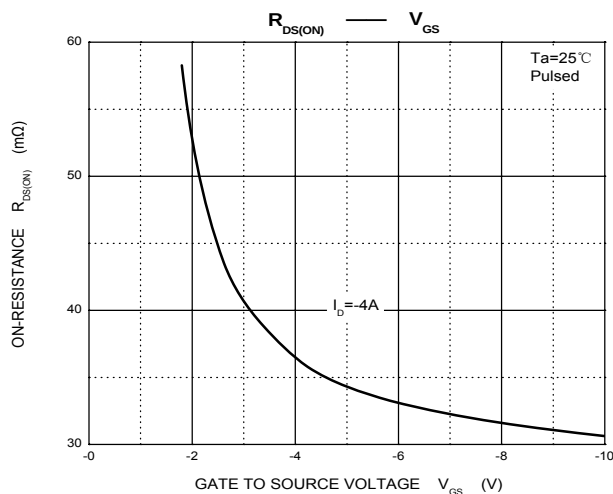
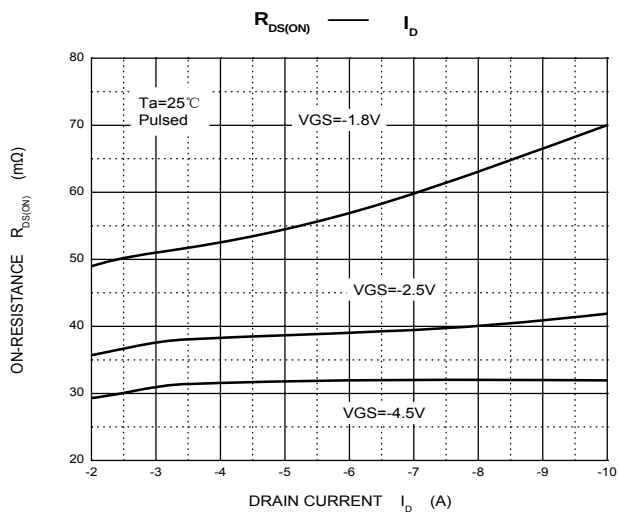
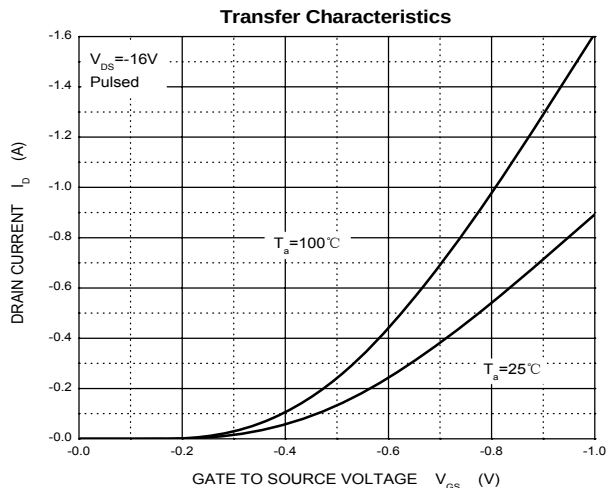
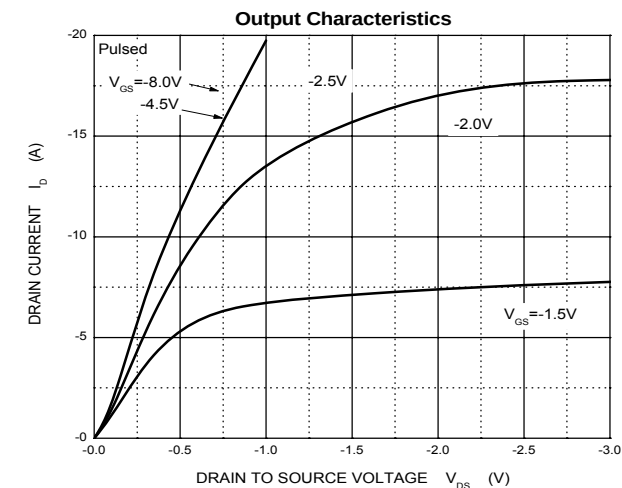
$T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static Parameters						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.3	-0.56	-1.2	
Gate-body leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 10	μA
		$V_{DS} = 0V, V_{GS} = \pm 4.5V$			± 1	
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -16V, V_{GS} = 0V$			-1	
Drain-source on-state resistance(note1)	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -4A$		0.030	0.045	Ω
		$V_{GS} = -2.5V, I_D = -3A$		0.038	0.060	
		$V_{GS} = -1.8V, I_D = -2A$		0.050	0.073	
Forward transconductance(note2)	g_{FS}	$V_{DS} = -5V, I_D = -4A$	8			S
Body diode voltage(note2)	V_{SD}	$I_S = -1A, V_{GS} = 0V$			-1	V
Dynamic Parameters (note3)						
Input capacitance	C_{iss}	$V_{DS} = -10V, V_{GS} = 0V, f = 1MHz$		1450		pF
Output capacitance	C_{oss}			205		
Reverse transfer capacitance	C_{rss}			160		
Gate resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		6.5		Ω
Switching Parameters						
Total gate charge	Q_g	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -4A$		17.2		nC
Gate-Source charge	Q_{gs}			1.3		
Gate-drain charge	Q_{gd}			4.5		
Turn-on delay time (note3)	$t_{d(on)}$	$V_{DS} = -10V, V_{GS} = -4.5V$ $R_{GEN} = 3\Omega, R_L = 2.5\Omega,$		9.5		ns
Turn-on rise time(note3)	t_r			17		
Turn-off delay time(note3)	$t_{d(off)}$			94		
Turn-off fall time(note3)	t_f			35		

Notes:

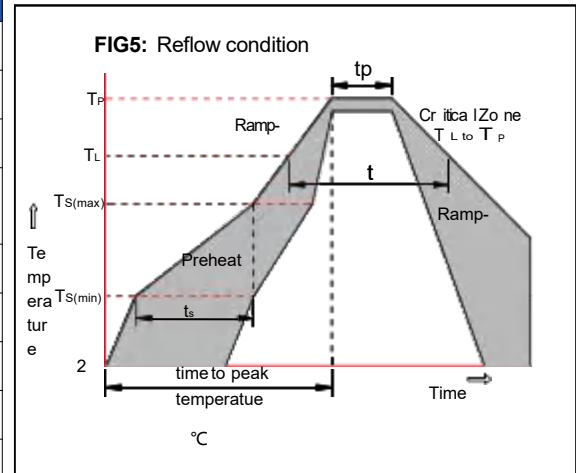
1. Repetitive rating, pulse width limited by junction temperature.
2. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. These parameters have no way to verify.

RATING AND CHARACTERISTIC CURVES



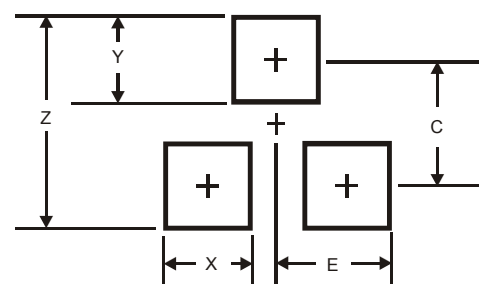
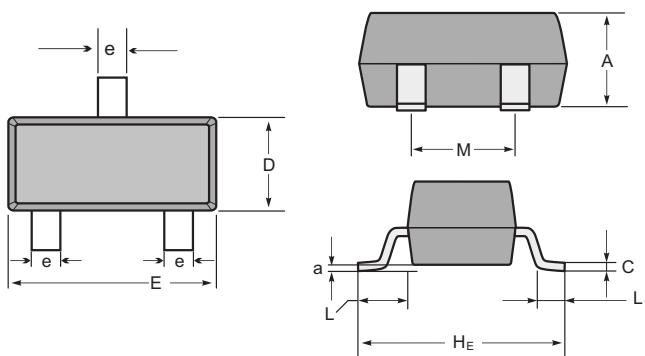
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23

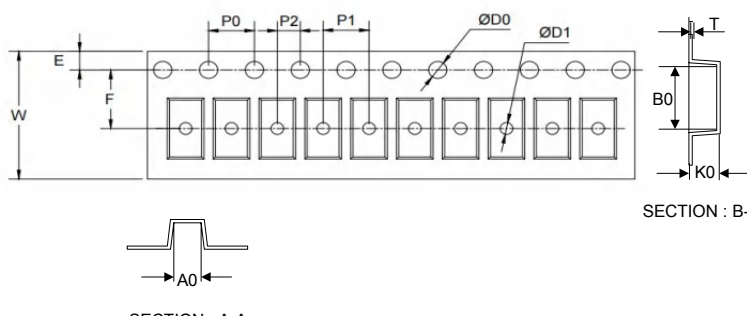
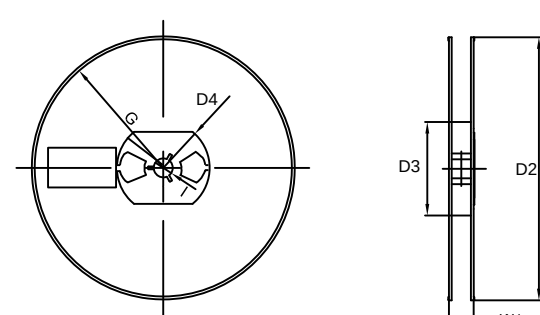


SOT-23 mechanical data

UNIT	A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7		0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)
	min	35	3	47	110	87	12	67		6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	1.55±0.10
		D1	1.05±0.10
		E	1.55±0.10
		F	3.60±0.10
		W	8.00±0.10
		A0	3.80±0.20
		B0	3.25±0.20
		K0	1.45±0.10
		T	0.25±0.05
		D2	178.0±3.0
		D3	55Min.
		D4	R24.0±3.0
7" Reel		G	R82.0±3.0
		I	13.0±2.0
		W1	11.0±3.0
		Quantity: 3000PCS	